

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STM32H733VGT6	221L*483XXZ	A	9991	28-10-2023
	Amount	UoM	Unit type	ST ECOPACK Grade
	681.44	mg	Each	ECOPACK® 2
	Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant (in each organic material)		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable ; if coating is used or other bulk termination : add in comments	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
QFP	14x14	100	L bend	
Comment	Package : 1L LQFP 100 14x14x1.4 1 0086901			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description

QueryList : REACH-14th June 2023				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				TRUE
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	221L*483XXXZ				5999999.0	1000001.0
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die or dies	M-011 Other inorganic materials	13.901	mg	Supplier	die	Silicon (Si)	7440-21-3		13.401	mg	964031	19666
				Supplier	metallization	Aluminium (Al)	7429-90-5		0.059	mg	4244	87
				Supplier	metallization	Copper (Cu)	7440-50-8		0.186	mg	13380	273
				Supplier	metallization	Nickel (Ni)	7440-02-0		0.001	mg	72	1
				Supplier	metallization	Tantalum (Ta)	7440-25-7		0.030	mg	2158	44
				Supplier	metallization	Titanium (Ti)	7440-32-6		0.005	mg	360	7
				Supplier	metallization	Tungsten (W)	7440-33-7		0.001	mg	72	1
				Supplier	Passivation	Silicon Oxide	7631-86-9		0.218	mg	15682	320
Leadframe (C7025 + Ag)	Copper & its alloys	190.000	mg	Supplier	Leadframe	Copper (Cu)	7440-50-8		174.610	mg	919000	256237
				Supplier	Leadframe	Nickel (Ni)	7440-02-0		5.890	mg	31000	8643
				Supplier	Leadframe	Silicon (Si)	7440-21-3		2.280	mg	12000	3346
				Supplier	Leadframe	Magnesium (Mg)	7439-95-4		0.570	mg	3000	836
				Supplier	Leadframe	Silver (Ag)	7440-22-4		6.650	mg	35000	9759
Glue Epoxy (EN-4900G)	Precious metals	2.800	mg	Supplier	Glue or tape	Silver (Ag)	7440-22-4		2.181	mg	779000	3201
				Supplier	Glue or tape	Cresol Novolac Epoxy Resins	Proprietary		0.070	mg	25000	103
				Supplier	Glue or tape	Bisphenol A Diacrylate	Proprietary		0.171	mg	61000	251
				Supplier	Glue or tape	Dicyclopentenyl group containing Acrylate	Proprietary		0.154	mg	55000	226
				Supplier	Glue or tape	Butadiene copolymer	Proprietary		0.028	mg	10000	41
				Supplier	Glue or tape	Polybutadiene epoxidized derivative	Proprietary		0.154	mg	55000	226
				Supplier	Glue or tape	Peroxy Ketals	Proprietary		0.014	mg	5000	21
				Supplier	Glue or tape	Substitutedalkoxyalkyl trimethoxysilane	Proprietary		0.014	mg	5000	21
Bonding wire (Cu)	Precious metals	1.200	mg	Supplier	Glue or tape	Methacrylate multialkoxy-substitutedalkyl ester	Proprietary		0.014	mg	5000	21
				Supplier	Bonding wire	Copper (Cu)	7440-50-8		1.159	mg	965500	1700
				Supplier	Bonding wire	Palladium (Pd)	7440-05-3		0.037	mg	31000	55
				Supplier	Bonding wire	Silver (Ag)	7440-22-4		0.004	mg	3500	6
Encapsulation (EME-G631SH)	M-011 Other inorganic materials	452.640	mg	Supplier	Molding Compound	2,2'-(3,3',5,5'-Tetramethyl-1,1'-biphenyl)-4,4'	85954-11-6		18.106	mg	40000	26570
				Supplier	Molding Compound	Epoxy resin	Proprietary		9.053	mg	20000	13285
				Supplier	Molding Compound	Phenol Resin	Proprietary		33.948	mg	75000	49818
				Supplier	Molding Compound	Silica(Amorphous) A	60676-86-0		321.148	mg	709500	471279
				Supplier	Molding Compound	Silica(Amorphous) B	7631-86-9		67.896	mg	150000	99636
External Plating (Sn)	M-011 Other inorganic materials	20.900	mg	Supplier	Molding Compound	Carbon black	1333-86-4		2.490	mg	5500	3653
				Supplier	Matte Sn	Tin (Sn)	7440-31-5		20.898	mg	999900	30667
				Supplier	Matte Sn	Impurities	-		0.002	mg	100	3